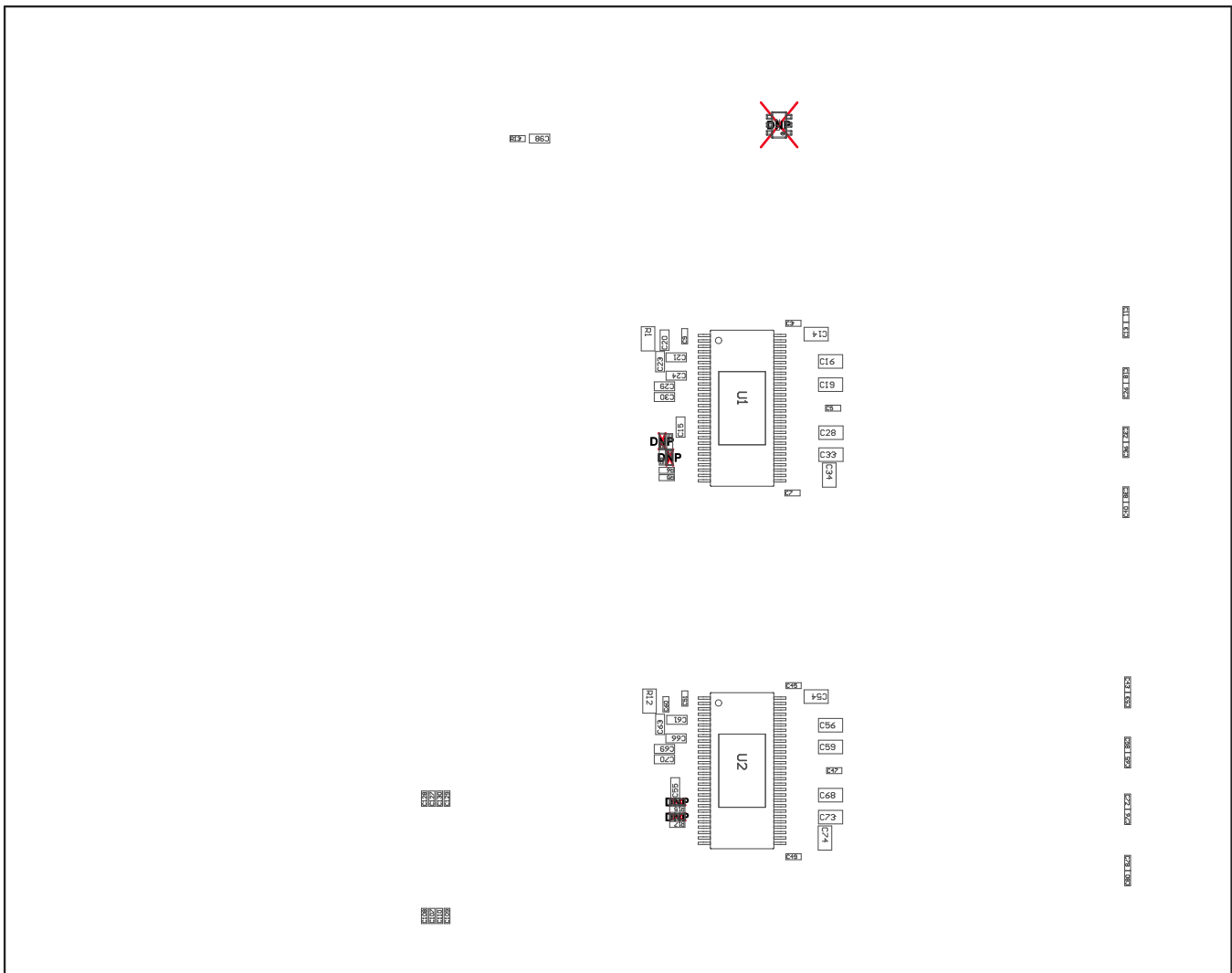


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA00733	REV: E	SUN REV: Not In VersionControl
	TID #: TIDA-00733		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/21/2017 2:24:55 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA00733	REV: E	SUN REV: Not In VersionControl
	TID #: TIDA-00733		
PLOTNAME = Bottom Assembly Drawing	GENERATED : 11/21/2017 2:24:57 PM	TEXAS INSTRUMENTS	

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